Thermal Conductivity and Interface Thermal Conductance of Phase Change Materials

David G. Cahill

Department of Materials Science, Materials Research Laboratory, University of Illinois, Urbana

> Ho-Ki Lyeo, KRISS, Daejoen, South Korea

Cheolkyu Kim and Yoonho Khang Samsung Advanced Institute of Technology, Yongin-Si, South Korea

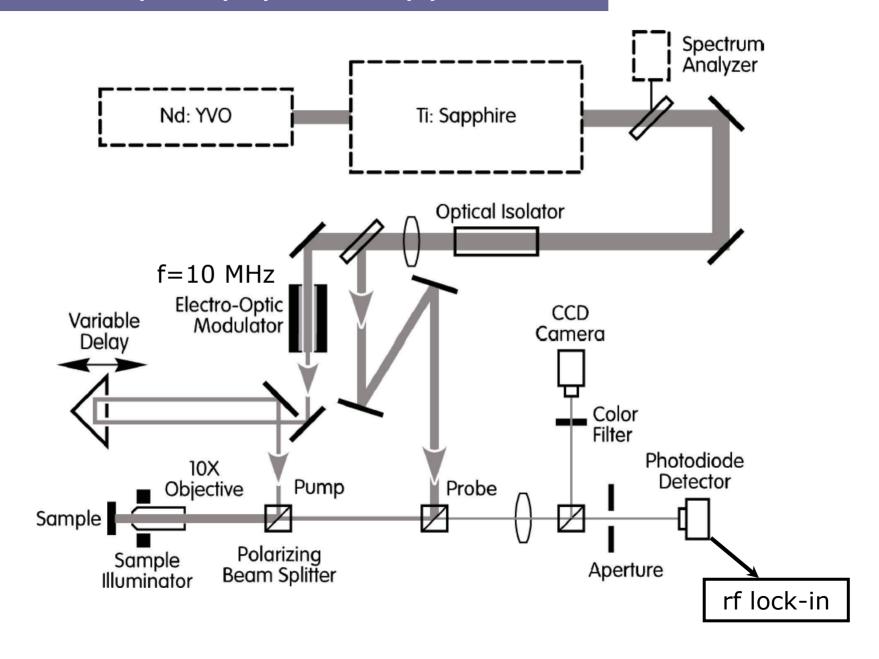




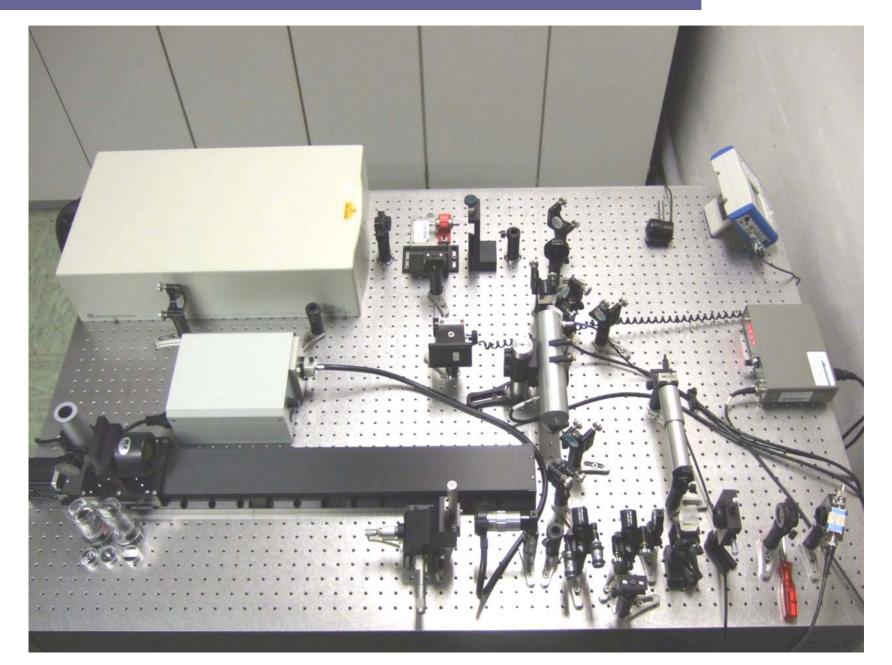
Outline

- Measurement: Modulated time-domain thermoreflectance (TDTR)
- Thermal conductivity: Phase change materials and the minimum thermal conductivity.
- Thermal conductance of interfaces with electrodes: Interfaces between highly dissimilar materials and anharmonic phonon transport.
- Controlling thermal conductance with thin interfacial layers: C₆₀ films (demonstrated); disordered layered crystals WSe₂ (proposed).

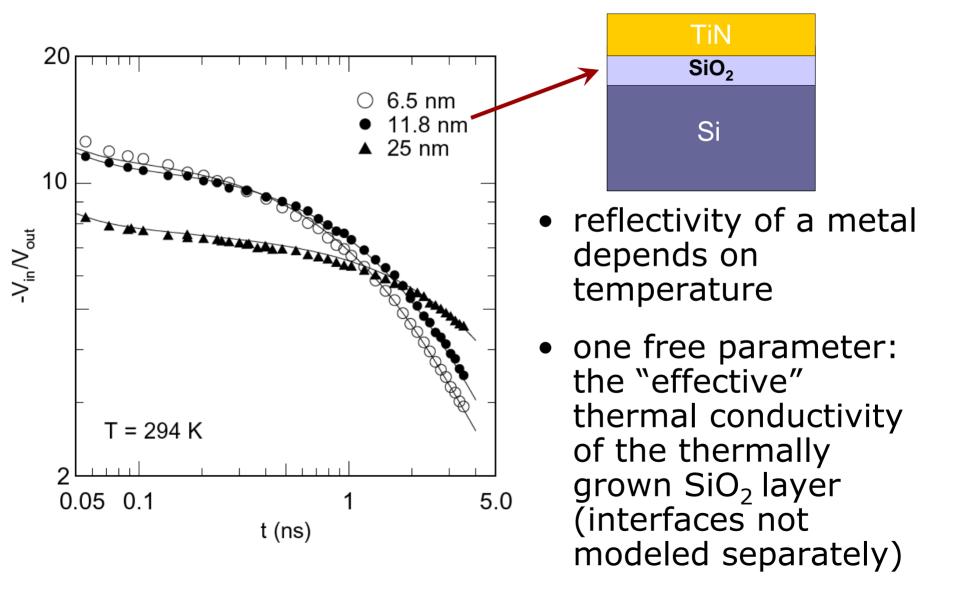
Modulated pump-probe apparatus



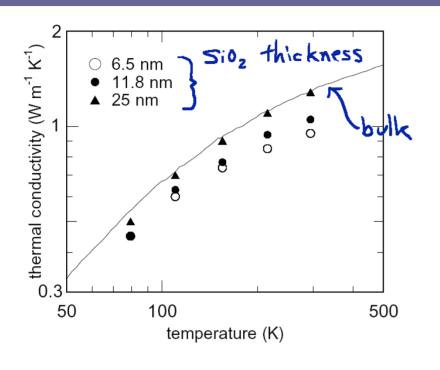
IPM system built January 7-8, 2008

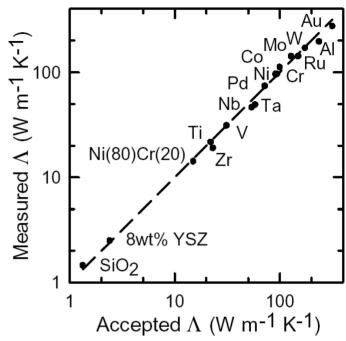


Time-domain Thermoreflectance (TDTR) data for TiN/SiO₂/Si



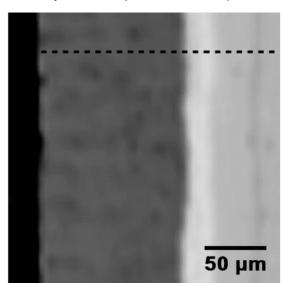
Flexible, convenient, and accurate technique...





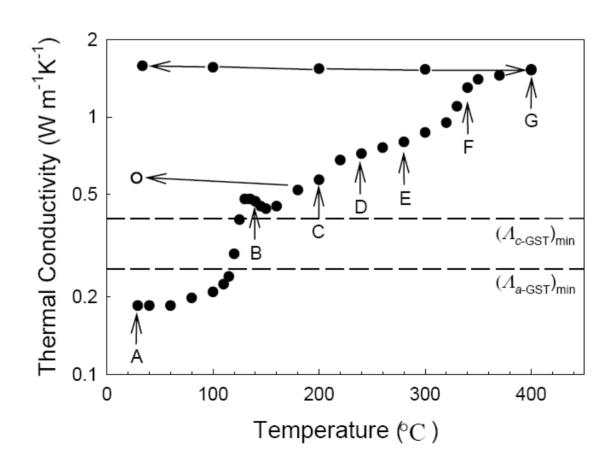
...with 3 micron resolution

thermal conductivity map of cross-section of thermal barrier coating, with J.-C. Zhao (GE)



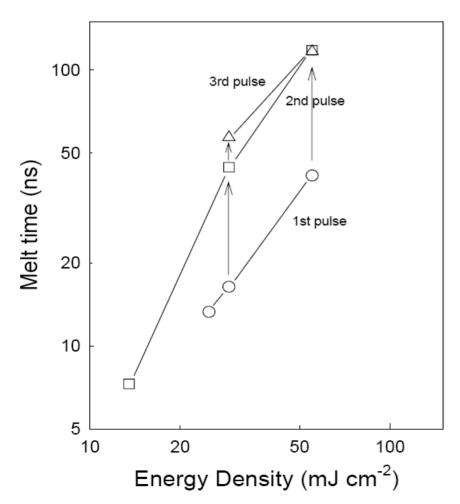
Ge₂Sb₂Te₅ during temperature ramp

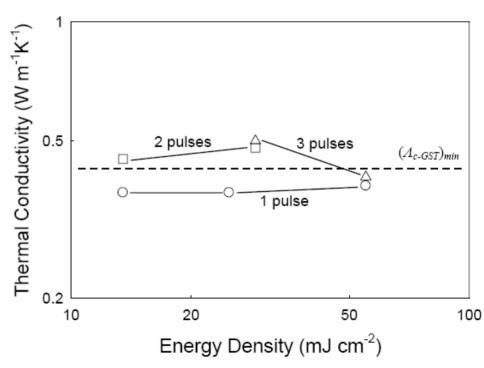
• Low conductivity in the cubic-phase (comparable to predicted Λ_{min}) increases modestly with annealing.



Cubic Ge₂Sb₂Te₅ formed by nsec laser pulse

• 523 nm, Q-switched doubled-YAG laser





Minimum thermal conductivity

 Both amorphous and "early" cubic phase have thermal conductivities comparable to the predicted minimum conductivity based on atomic density n and speeds of sound v.

High T limit
$$\Lambda_{\min} = \frac{1}{2} \left(\frac{\pi}{6} \right)^{1/3} k_B n^{2/3} (v_l + 2v_t)$$

- v_i measured directly by picosecond acoustics
- Assume $v_t = 0.6 v_l$

Thermal conductivity and interface thermal conductance

Thermal conductivity
Λ is a property of the continuum

$$\vec{\mathcal{T}} = -\Lambda \vec{\nabla} T \qquad \qquad \vec{\nabla} \vec{T} \qquad \Lambda = \frac{1}{3Vk_BT^2} \int_0^\infty \langle \vec{\jmath}(t) \cdot \vec{\jmath}(0) \rangle dt$$

• Thermal conductance (per unit area) *G* is a property of an interface

$$\mathcal{J} = \mathbf{G}\Delta \mathcal{T}$$

$$G = \frac{1}{Ak_BT^2} \int_0^\infty \langle q(t)q(0)\rangle \, dt$$

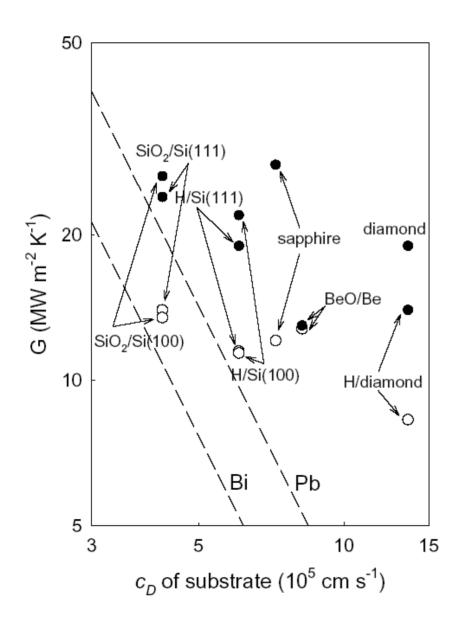
$$\Delta \mathcal{T} \text{ at interface}$$

Interface thermal conductance between GST and electrodes

- Difficult to measure because thermal conductivities are small and, for c-GST, depends on thickness; see Reifenberg et al. (2007) and Lee et al. (2000).
- And hard to predict because analytical models do not include anharmonicity or details of the interface structure and bonding.
- high temperature limit of the radiation limit

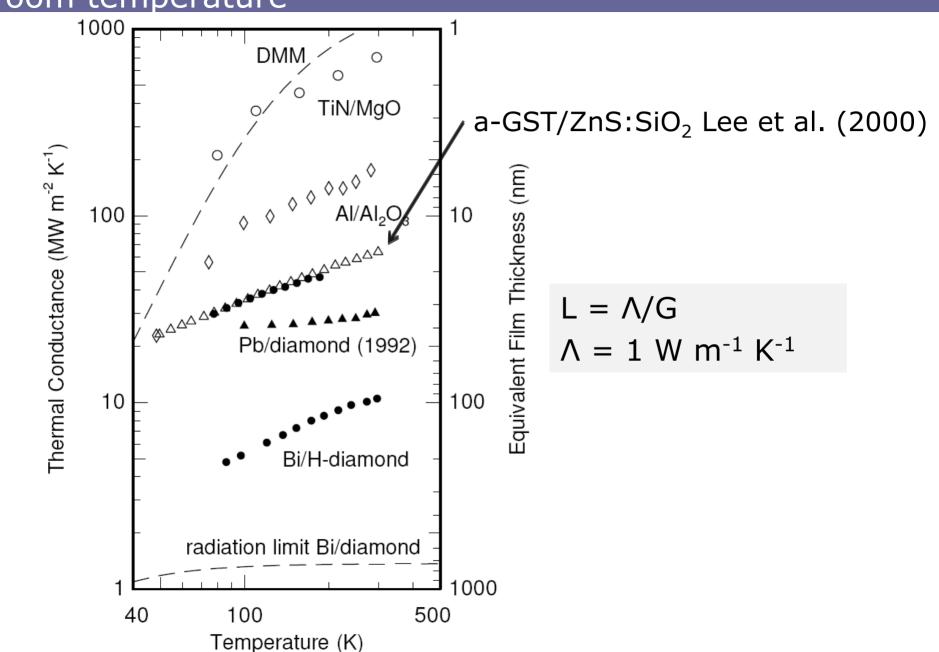
R. J. Stoner and H. J. Maris, *Phys.Rev.B* **48**, 22, 16373 (1993)

Room temperature thermal conductance



- Pb and Bi show similar behavior. Electronphonon coupling is not an important channel.
- Weak dependence on Debye velocity of the substrate.
- For Pb and Bi, conductance always larger than predicted by a purely elastic process.

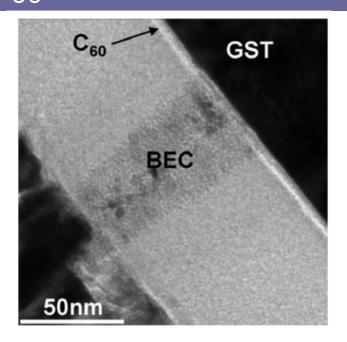
Interface thermal conductance: Factor of 60 range at room temperature

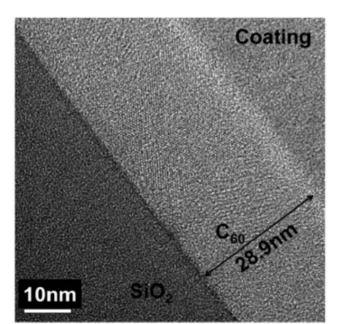


Bottom line...

- Thermal conductance of Ge₂Sb₂Te₅/nitride interfaces is not known precisely. Limited data and analogy to Pb interfaces suggests G ≈25 MW m⁻² K⁻¹ at room temperature.
- Kapitza length $L = \Lambda/G \approx 10 \text{ nm for a-Ge}_2Sb_2Te_5$
- Not yet measured but G will probably increase significantly with temperature.
- For liquid (metallic) Ge₂Sb₂Te₅, conductance will become large because of electronic thermal transport.

C₆₀ fullerene as thermal insulation



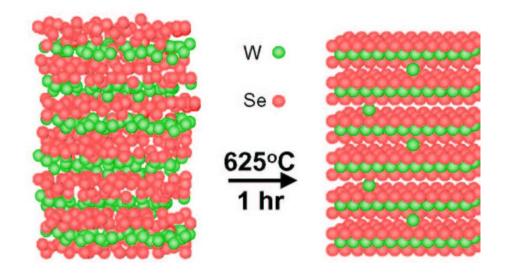


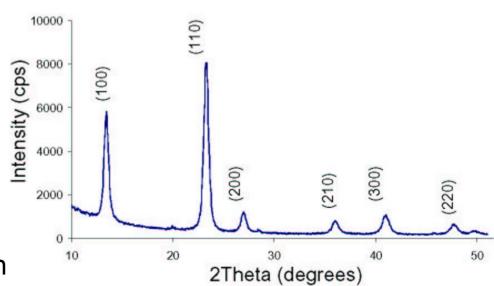
- Evaporate C₆₀ on TiN or TiAlN back-electrode contacts
- Add Ge₂Sb₂Te₅ layer (or not)
- Coat with Al for thermal transport measurements by time-domain thermoreflectance

C₆₀ fullerene as thermal insulation Al 100 **C**60 TiN or TiAIN Thermal conductance (MW ${\sf m}^{\text{-2}}\;{\sf K}^{\text{-1}}$) AI/C₆₀/TiN Al Al/C₆₀/TiAlN **GST C**₆₀ 10 TiN or TiAIN Fit gives interface Al/c-GST/C₆₀/TiN conductance and Al/c-GST/C₆₀/TiAlN conductivity of C₆₀ $G=13 MW m^{-2} K^{-1}$ 30 10 $\Lambda = 0.13 \text{ W m}^{-1} \text{ K}^{-1}$ C₆₀ film thickness (nm)

Layered disordered crystals: WSe₂ by "modulated elemental reactants"

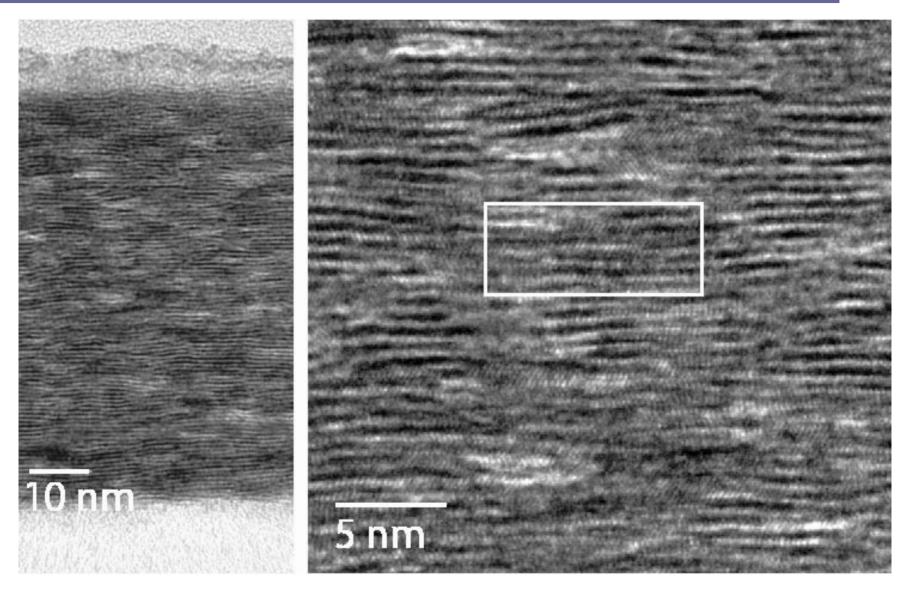
- Deposit W and Se layers at room temperature on Si substrates
- Anneal to remove excess Se and improve crystallinity
- Characterize by RBS, x-ray diffraction (lab sources and Advanced Photon Source) and TEM





David Johnson group, U. Oregon

Cross-sectional TEM of 60 nm thick WSe₂

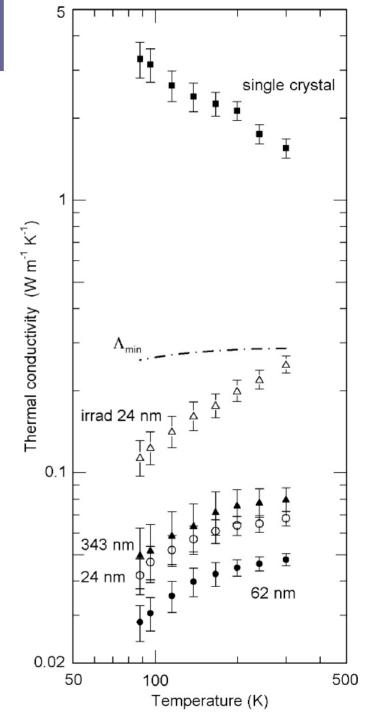


Seongwon Kim and Jian Min Zuo

Thermal conductivity of WSe₂

- 60 nm film has the lowest thermal conductivity ever observed in a fully dense solid. Only twice the thermal conductivity of air.
- A factor of 6 less than the calculated amorphous limit for this material.

Chiritescu et al. Science (2006)



Conclusions

- Thermal conductivity of amorphous and "early" cubic phase and laser crystallized cubic phase are all comparable to the predicted minimum thermal conductivity → strong disorder in the crystal
- Thermal conductance of interfaces with nitride electrodes is equivalent to ≈10 nm thick layer of amorphous GST, decreases with thickness.
- C_{60} layer provides thermal resistance equivalent to ≈ 20 nm thick layer of amorphous GST
- Could, in principle produce the same thermal resistance with a 5 nm thick layer of a *disordered* layered crystal such as WSe₂.